

## Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- Two Diode Elements Connected in a Common Anode Configuration
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Note 3)**
- **The BAW56Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

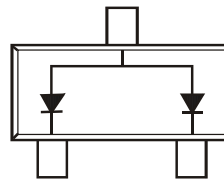
<https://www.diodes.com/quality/product-definitions/>

## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Lead-Frame (Lead-Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.008 grams (Approximate)



Top View



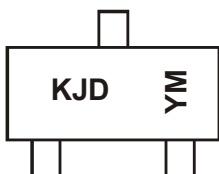
Top View  
Internal Schematic

## Ordering Information (Note 4)

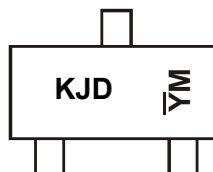
Part Number	Compliance	Case	Packaging
BAW56-7-F	Standard	SOT23	3,000/Tape & Reel
BAW56-13-F	Standard	SOT23	10,000/Tape & Reel
BAW56Q-7-F	Automotive	SOT23	3,000/Tape & Reel
BAW56Q-13-F	Automotive	SOT23	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



SAT (Shanghai Assembly / Test Site)  
 KJD = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: H = 2020)  
 M = Month (ex: 9 = September)



CAT (Chengdu Assembly / Test Site)  
 KJD = Product Type Marking Code  
 YM = Date Code Marking for Chengdu  
 Y = Year (ex: H = 2020)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2002	...	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	O	...	H	I	J	K	L	M	N	O	P	R

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V
Peak Repetitive Reverse Voltage	$V_{RRM}$	75	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Continuous Current (Note 5)	$I_{FM}$	300	mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	@ $t = 1.0\mu\text{s}$ 2.0	A
		@ $t = 1.0\text{s}$ 1.0	

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Power Dissipation (Note 5)	$P_D$	350	mW
Typical Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	75	—	V	$I_R = 2.5\mu\text{A}$
Forward Voltage	$V_F$	—	0.715 0.855 1.0 1.25	V	$I_F = 1.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 50\text{mA}$ $I_F = 150\text{mA}$
Reverse Current (Note 6)	$I_R$	—	2.5 50 30 25	$\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$ nA	$V_R = 75\text{V}$ $V_R = 75\text{V}, T_J = +150^\circ\text{C}$ $V_R = 25\text{V}, T_J = +150^\circ\text{C}$ $V_R = 20\text{V}$
Total Capacitance	$C_T$	—	2.0	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{RR}$	—	4.0	ns	$I_F = I_R = 10\text{mA}$ , $I_{RR} = 0.1 \times I_R, R_L = 100\Omega$

Notes: 5. Part mounted on FR-4 substrate PC board with 1inch squared, 2oz copper pad layout.  
6. Short duration pulse test used to minimize self-heating effect.

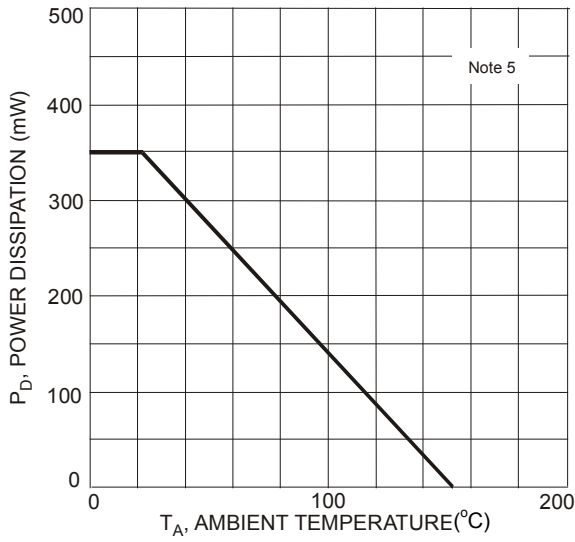


Fig. 1 Power Derating Curve, Total Package

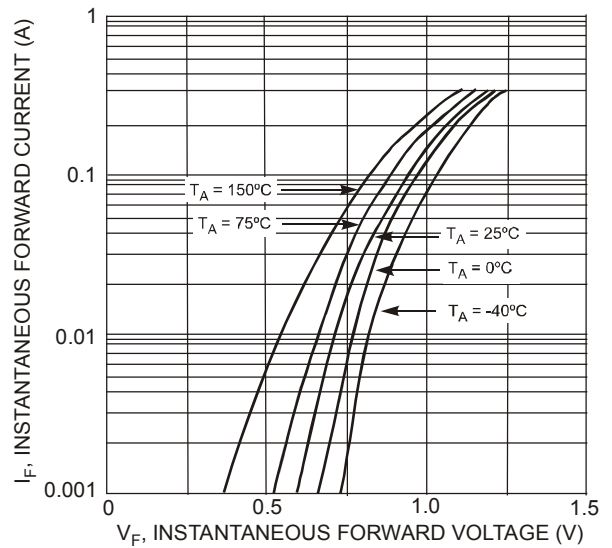


Fig. 2 Typical Forward Characteristics, Per Element

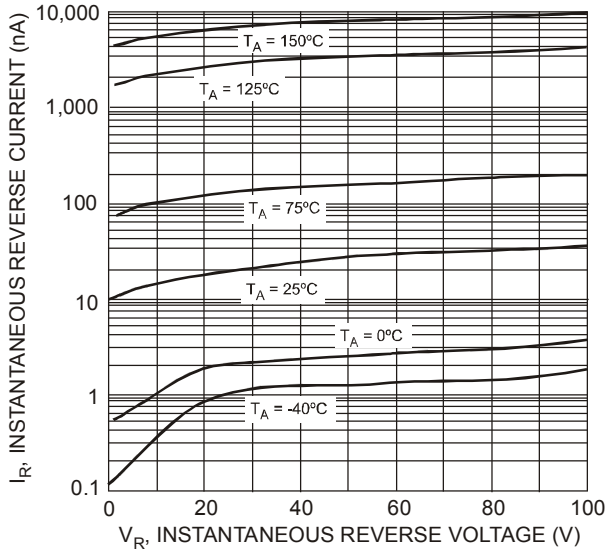


Fig. 3 Typical Reverse Characteristics, Per Element

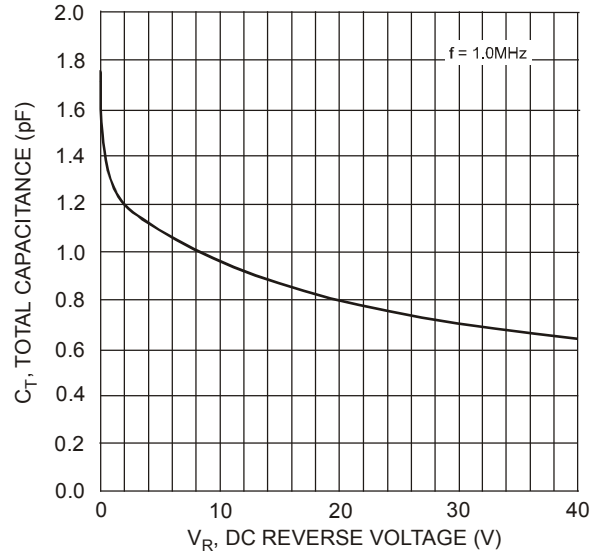
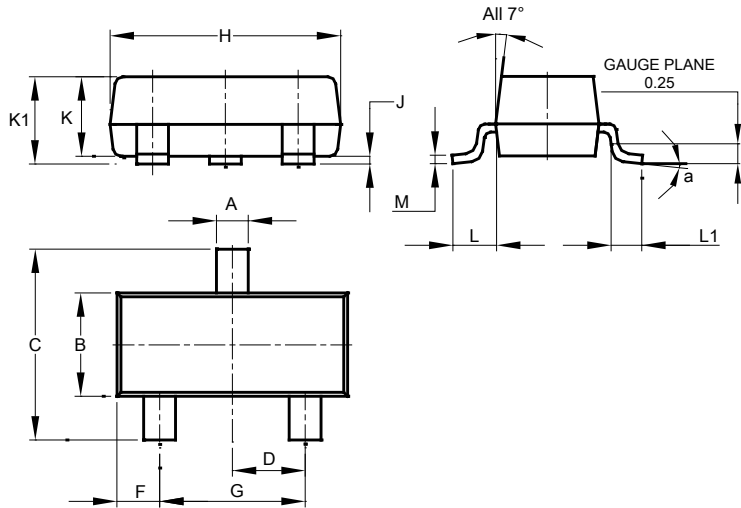


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**

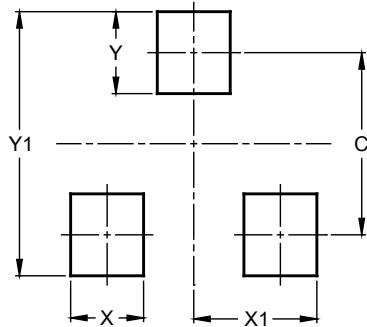


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9